

REVISIONS

LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
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PRELIMINARY (5/22/09) – FOR INFORMATION ONLY

NOT TO BE USED FOR PROCUREMENT

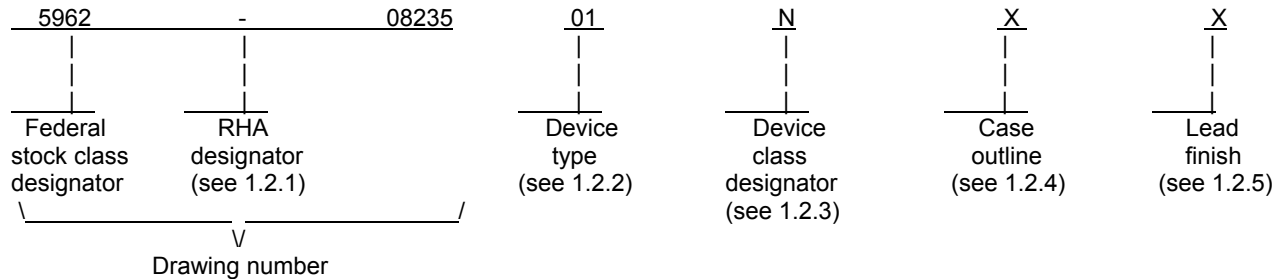
REV SHEET																				
REV SHEET	15	16	17	18	19	20	21	22												
REV STATUS OF SHEETS	REV SHEET			1	2	3	4	5	6	7	8	9	10	11	12	13	14			

PMIC N/A	PREPARED BY	DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990 http://www.dsccl.dla.mil				
STANDARD MICROCIRCUIT DRAWING THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE AMSC N/A	CHECKED BY	MICROCIRCUIT, MEMORY, DIGITAL, 512K X 36 SYNCHRONOUS STATIC RANDOM ACCESS MEMORY (SRAM), 3.3 V, MONOLITHIC SILICON				
	APPROVED BY					
	DRAWING APPROVAL DATE	SIZE A	CAGE CODE 67268	5962-08235		
	REVISION LEVEL	SHEET 1 OF 24				

1. SCOPE

1.1 Scope. This drawing documents three product assurance class levels consisting of high reliability (device class Q), space application (device class V) and nontraditional performance environment (device class N). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels are reflected in the PIN.

1.2 PIN. The PIN is as shown in the following example:



1.2.1 RHA designator. Device classes N, Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device type(s). The device type(s) identify the circuit function as follows:

<u>Device type</u>	<u>Generic number 1/</u>	<u>Circuit function</u>	<u>Maximum operating speed</u>
01		128K X 32 CMOS SRAM	250 MHz
02		128K X 32 CMOS SRAM	200 MHz
03		128K X 32 CMOS SRAM	167 MHz

1.2.3 Device class designator. The device class designator is a single letter identifying the product assurance level as follows:

<u>Device class</u>	<u>Device requirements documentation</u>
N	Certification and qualification to MIL-PRF-38535 for plastic encapsulated microcircuit (PEM)
Q or V	Certification and qualification to MIL-PRF-38535

1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
X	See figure 1	100	Thin quad flat pack (TQFP)
Y	See figure 1	119	Plastic ball grid array (PBGA)
Z	See figure 1	165	Fine pitch ball grid array (FBGA)

1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38535 for device classes N, Q and V.

1/ Generic numbers are listed on the Standard Microcircuit Drawing Source Approval Bulletin at the end of this document and will also be listed in MIL-HDBK-103 (see 6.6.2 herein).

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1.3 Absolute maximum ratings. 2/

Supply voltage range (V _{DD}) -----	-0.5 V dc to + 4.6 V dc
Voltage range on any input -----	-0.5 V dc to V _{DD} + 0.5 V dc
Voltage range on any output pin -----	-0.5 V dc to V _{DDQ} + 0.5 V dc
Storage temperature range -----	-65°C to +150°C
Maximum power dissipation (P _D) -----	
01-----	1.61 W
02-----	1.38 W
03-----	1.27 W
Lead temperature (soldering, 10 seconds)----	+260°C
Thermal resistance, junction-to-case (Θ _{JC}):	
Case X -----	4.08 °C/W 3/
Case Y -----	6.2 °C/W 3/
Case Z -----	4.0 °C/W 3/
Junction temperature (T _J) -----	+140°C 4/
Output current -----	20 mA

1.4 Recommended operating conditions.

Supply voltage range (V _{DD}) -----	3.135 V dc to 3.6 V dc
Supply voltage to outputs (V _{DDQ}) -----	2.375 V dc to V _{DD}
Supply voltage (V _{SS}) -----	0 V
Input high voltage range (V _{IH}) for 3.3 V I/O ----	2.0 V dc to V _{DD} + 0.3 V dc 5/
Input high voltage range (V _{IH}) for 2.5 V I/O ----	1.7 V dc to V _{DD} + 0.3 V dc 5/
Input low voltage range (V _{IL}) for 3.3 V I/O ----	-0.3 V dc to 0.8 V dc 5/
Input low voltage range (V _{IL}) for 2.5 V I/O ----	-0.3 V dc to 0.7 V dc 5/
Case operating temperature range (T _C)-----	-55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.
MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <http://assist.daps.dla.mil/quicksearch/> or <http://assist.daps.dla.mil> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Non-Government publications. The following document(s) form a part of this document to the extent specified herein. Unless otherwise specified, the issues of the documents are the issues of the documents cited in the solicitation.

AMERICAN SOCIETY FOR TESTING AND MATERIALS (ASTM)

2/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

3/ Tested initially and after any design or process changes that may affect these parameters.

4/ Maximum junction temperature shall not be exceeded except for allowable short duration burn-in screening conditions in accordance with method 5004 of MIL-STD-883.

5/ Overshoot: V_{IH}(AC) < V_{DDQ} + 1.5V (Pulse width less than t_{CYC}/2), Undershoot: V_{IL}(AC) > -2V (Pulse width less than t_{CYC}/2).

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ASTM Standard F1192-95 - Standard Guide for the Measurement of Single Event Phenomena from Heavy Ion Irradiation of Semiconductor Devices.

(Applications for copies of ASTM publications should be addressed to: ASTM International, PO Box C700, 100 Barr Harbor Drive, West Conshohocken, PA 19428-2959; <http://www.astm.org>.)

ELECTRONICS INDUSTRIES ASSOCIATION (EIA)

JEDEC Standard EIA/JESD78 -

JEDEC Solid State Product Outline MS-026 -

JEDEC Solid State Product Outline MO-216 -

IC Latch-Up Test.

Low/Thin Profile Plastic Quad Flat Package,

2.00 mm Footprint, Optional Heat Slug

Thin Profile, Square and Rectangular, Ball Grid Array Family,
1.00 & 0.80MM Pitches.

(Applications for copies should be addressed to the Electronics Industries Association, 2500 Wilson Boulevard, Arlington, VA 22201; <http://www.jedec.org>.)

(Non-Government standards and other publications are normally available from the organizations that prepare or distribute the documents. These documents also may be available in or through libraries or other informational services.)

2.3 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements for device classes N, Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes N, Q and V.

3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.

3.2.3 Truth table(s). The truth table(s) shall be as specified on figure 3.

3.2.4 Functional tests. Various functional tests are used to test this device. If the test patterns cannot be implemented due to test equipment limitations, alternate test patterns to accomplish the same results shall be allowed. For device classes N, Q and V alternate test patterns shall be under the control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the preparing or acquiring activity upon request.

3.3 Electrical performance characteristics and postirradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full case operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.

3.5 Marking. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes N, Q and V shall be in accordance with MIL-PRF-38535

3.5.1 Certification/compliance mark. The certification mark for device classes N, Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535.

3.6 Certificate of compliance. For device classes N, Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes N, Q and V, the requirements of MIL-PRF-38535.

3.7 Certificate of conformance. A certificate of conformance as required for device classes N, Q and V in MIL-PRF-38535 shall be provided with each lot of microcircuits delivered to this drawing.

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TABLE I. Electrical performance characteristics

Test	Symbol	Conditions -55° ≤ T _C ≤ 125°C 3.135 V ≤ V _{DD} ≤ 3.6 V 2.375 V ≤ V _{DDQ} ≤ V _{DD} Unless Otherwise Specified 2/ 3/		Group A Subgroups	Device Type	Limits		Units
						Min	Max	
Output HIGH Voltage	V _{OH}	for 3.3 V I/O, I _{OH} = -4.0 mA		1, 2, 3	All	2.4	---	V
		for 2.5 V I/O, I _{OH} = -1.0 mA				2.0	---	
Output LOW Voltage	V _{OL}	for 3.3 V I/O, I _{OL} = 8.0 mA		1, 2, 3	All	---	0.4	V
		for 2.5 V I/O, I _{OL} = 1.0 mA				---	0.4	
Input HIGH Voltage	V _{IH}	for 3.3 V I/O		1, 2, 3	All	2.0	V _{DD} + 0.3 V	V
		for 2.5 V I/O				1.7	V _{DD} + 0.3 V	
Input LOW Voltage	V _{IL}	for 3.3 V I/O		1, 2, 3	All	-0.3	0.8	V
		for 2.5 V I/O				-0.3	0.7	
Input Leakage Current	I _X	Input Leakage Current except ZZ and MODE	GND ≤ V _I ≤ V _{DDQ}	1, 2, 3	All	-5	5	uA
						Input Current of MODE	Input = V _{SS}	
		Input = V _{DD}	5					
		Input Current of ZZ	Input = V _{SS}			---		
Input = V _{DD}	30							
Output Leakage Current	I _{oz}	GND ≤ V _I ≤ V _{DDQ} , output disabled		1, 2, 3	All	-5	5	uA
V _{CC} Operating Supply Current	I _{DD}	V _{DD} = max, I _{OUT} =0 mA f = f _{MAX} = 1/t _{CYC}	4-ns cycle, 250 MHz	1, 2, 3	01	---	350	mA
			5-ns cycle, 200 MHz		02	---	300	
			6-ns cycle, 167 MHz		03	---	275	
Automatic CE Power-Down Current - TTL Inputs	I _{SB1}	V _{DD} = max, device deselected, V _{IN} ≥ V _{IH} or V _{IN} ≤ V _{IL} f = f _{MAX} = 1/t _{CYC}	4-ns cycle, 250 MHz	1, 2, 3	01	---	160	mA
			5-ns cycle, 200 MHz		02	---	150	mA
			6-ns cycle, 167 MHz		03	---	140	mA
Automatic CE Power-Down Current - CMOS Inputs	I _{SB2}	V _{DD} = max, device deselected, V _{IN} ≤ 0.3V or V _{IN} ≥ V _{DDQ} - 0.3V, f = 0	All speeds	1, 2, 3	All	---	70	mA
Automatic CE Power-Down Current - CMOS Inputs	I _{SB3}	V _{DD} = max, device deselected or V _{IN} ≤ 0.3V or V _{IN} ≥ V _{DDQ} - 0.3V, f = f _{MAX} = 1/t _{CYC}	4-ns cycle, 250 MHz	1, 2, 3	01	---	135	mA
			5-ns cycle, 200 MHz		02	---	130	
			6-ns cycle, 167MHz		03	---	125	

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55° ≤ T _C ≤ 125°C 3.135 V ≤ V _{DD} ≤ 3.6 V 2.375 V ≤ V _{DDQ} ≤ V _{DD} Unless Otherwise Specified <u>2/</u> <u>3/</u>		Group A Subgroups	Device Type	Limits		Units
						Min	Min	
Automatic CE Power-Down Current - TTL Inputs	I _{SB4}	V _{DD} = max, device deselected, V _{IN} ≥ V _{IH} or V _{IN} ≤ V _{IL} , f = 0	All speeds	1, 2, 3	All		80	mA
Snooze Mode Standby current	I _{DDZZ}	ZZ ≥ V _{DD} - 0.2V		1, 2, 3	All		80	mA
Input Capacitance <u>1/</u>	C _{IN}	T _A = 25°C, f = 1 MHz, V _{DD} = 3.3V V _{DDQ} = 3.3V	Case X	4	All		5	pF
			Case Y				8	
			Case Z				9	
Clock Input Capacitance <u>1/</u>	C _{CLK}		Case X	4	All		5	pF
			Case Y				8	
			Case Z				9	
Input/Output Capacitance <u>1/</u>	C _{I/O}		Case X	4	All		5	pF
			Case Y				8	
			Case Z				9	

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55° ≤ T _C ≤ 125°C 3.135 V ≤ V _{DD} ≤ 3.6 V 2.375 V ≤ V _{DDQ} ≤ V _{DD} Unless Otherwise Specified 2/ 3/	Group A Subgroups	Device Type	Limits		Units
					Min	Max	
Clock Cycle Time	t _{CYC}	See Figure 5 as applicable. 4/ 8/ 9/	9, 10, 11	01	4.0	---	ns
				02	5.0	---	
				03	6.0	---	
Clock HIGH	t _{CH}		9, 10, 11	01	1.7	---	ns
				02	2.0	---	
				03	2.2	---	
Clock LOW	t _{CL}		9, 10, 11	01	1.7	---	ns
				02	2.0	---	
				03	2.2	---	
Data Output valid after CLK rise	t _{CO}		9, 10, 11	01	---	2.6	ns
				02	---	3.0	
				03	---	3.4	
Data Output hold after CLK rise	t _{DOH}		9, 10, 11	01	1.0	---	ns
				02	1.3	---	
				03	1.3	---	
Clock to Low-Z 5/ 6/ 7/	t _{CLZ}	9, 10, 11	01	1.0	---	ns	
			02	1.3	---		
			03	1.3	---		
Clock to High-Z 5/ 6/ 7/	t _{CHZ}	9, 10, 11	01	---	2.6	ns	
			02	---	3.0		
			03	---	3.4		
OE Low to Output valid	t _{OEV}	9, 10, 11	01	---	2.6	ns	
			02	---	3.0		
			03	---	3.4		
OE Low to Output Low-Z 5/ 6/ 7/	t _{OELZ}	9, 10, 11	01	0	---	ns	
			02	0	---		
			03	0	---		
OE High to Output High-Z 5/ 6/ 7/	t _{OEHZ}	9, 10, 11	01	---	2.6	ns	
			02	---	3.0		
			03	---	3.4		
Address setup before CLK rise	t _{AS}	9, 10, 11	01	1.2	---	ns	
			02	1.4	---		
			03	1.5	---		
Data Input Setup before CLK rise	t _{DS}	9, 10, 11	01	1.2	---	ns	
			02	1.4	---		
			03	1.5	---		
CEN setup before CLK rise	t _{CENS}	9, 10, 11	01	1.2	---	ns	
			02	1.4	---		
			03	1.5	---		
WE, BW _x Setup before CLK rise	t _{WES}	9, 10, 11	01	1.2	---	ns	
			02	1.4	---		
			03	1.5	---		
ADV/ LD Setup before CLK rise	t _{ALS}	9, 10, 11	01	1.2	---	ns	
			02	1.4	---		
			03	1.5	---		

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55° ≤ T _C ≤ 125°C 3.135 V ≤ V _{DD} ≤ 3.6 V 2.375 V ≤ V _{DDQ} ≤ V _{DD} Unless Otherwise Specified <u>2/ 3/</u>	Group A Subgroups	Device Type	Limits		Units
					Min	Max	
Chip Enable setup before CLK rise	t _{CES}	See Figure 5 as applicable. <u>4/ 8/ 9/</u>	9, 10, 11	01	1.2	---	ns
				02	1.4	---	
				03	1.5	---	
Address Hold after CLK rise	t _{AH}		9, 10, 11	01	0.3	---	ns
				02	0.4	---	
				03	0.5	---	
Data Input hold after CLK rise	t _{DH}		9, 10, 11	01	0.3	---	ns
				02	0.4	---	
				03	0.5	---	
$\overline{\text{CEN}}$ hold after CLK rise	t _{CENH}		9, 10, 11	01	0.3	---	ns
				02	0.4	---	
				03	0.5	---	
$\overline{\text{WE}}$, $\overline{\text{BW}}_x$ hold after CLK rise	t _{WEH}		9, 10, 11	01	0.3	---	ns
				02	0.4	---	
		03		0.5	---		
ADV/ $\overline{\text{LD}}$ hold after CLK rise	t _{ALH}	9, 10, 11	01	0.3	---	ns	
			02	0.4	---		
			03	0.5	---		
Chip Enable hold after CLK rise	t _{CEH}	9, 10, 11	01	0.3	---	ns	
			02	0.4	---		
			03	0.5	---		
Device Operation to ZZ	t _{ZZS}	ZZ ≥ V _{DD} - 0.2V	9, 10, 11	All	---	2t _{CYC}	ns
ZZ recovery time	t _{ZZREC}	ZZ ≤ 0.2V	9, 10, 11	All	2t _{CYC}	---	ns
ZZ active to snooze current <u>7/</u>	t _{ZZI}		9, 10, 11	All	---	2t _{CYC}	ns
ZZ inactive to exit snooze current <u>7/</u>	t _{RZZI}		9, 10, 11	All	0	---	ns

1/ Tested initially and after any design or process changes that may affect these parameters.

2/ All voltage referenced to ground.

3/ Overshoot: V_{IH}(AC) < V_{DDQ} + 1.5V (Pulse width less than t_{CYC}/2), Undershoot: V_{IL}(AC) > -2 (Pulse width less than t_{CYC}/2).

4/ Power up: Assumes a linear ramp from 0V to V_{DD}(min) within 200 ms. During this time, V_{IH} < V_{DD} and V_{DDQ} ≤ V_{DD}.

5/ t_{CHZ}, t_{CLZ}, t_{OELZ}, and t_{OEHZ} are specified with AC test conditions shown in Figure 4 (b), AC Test Loads. Transition is measured ± 200 mV from steady-state voltage.

6/ At any given voltage and temperature, t_{OEHZ} is less than t_{OELZ} and t_{CHZ} is less than t_{CLZ} to eliminate bus contention between SRAMs when sharing the same data bus. These specifications do not imply a bus contention condition, but reflect parameters guaranteed over worst case user conditions. Device is designed to achieve High-Z prior to Low-Z under the same system conditions.

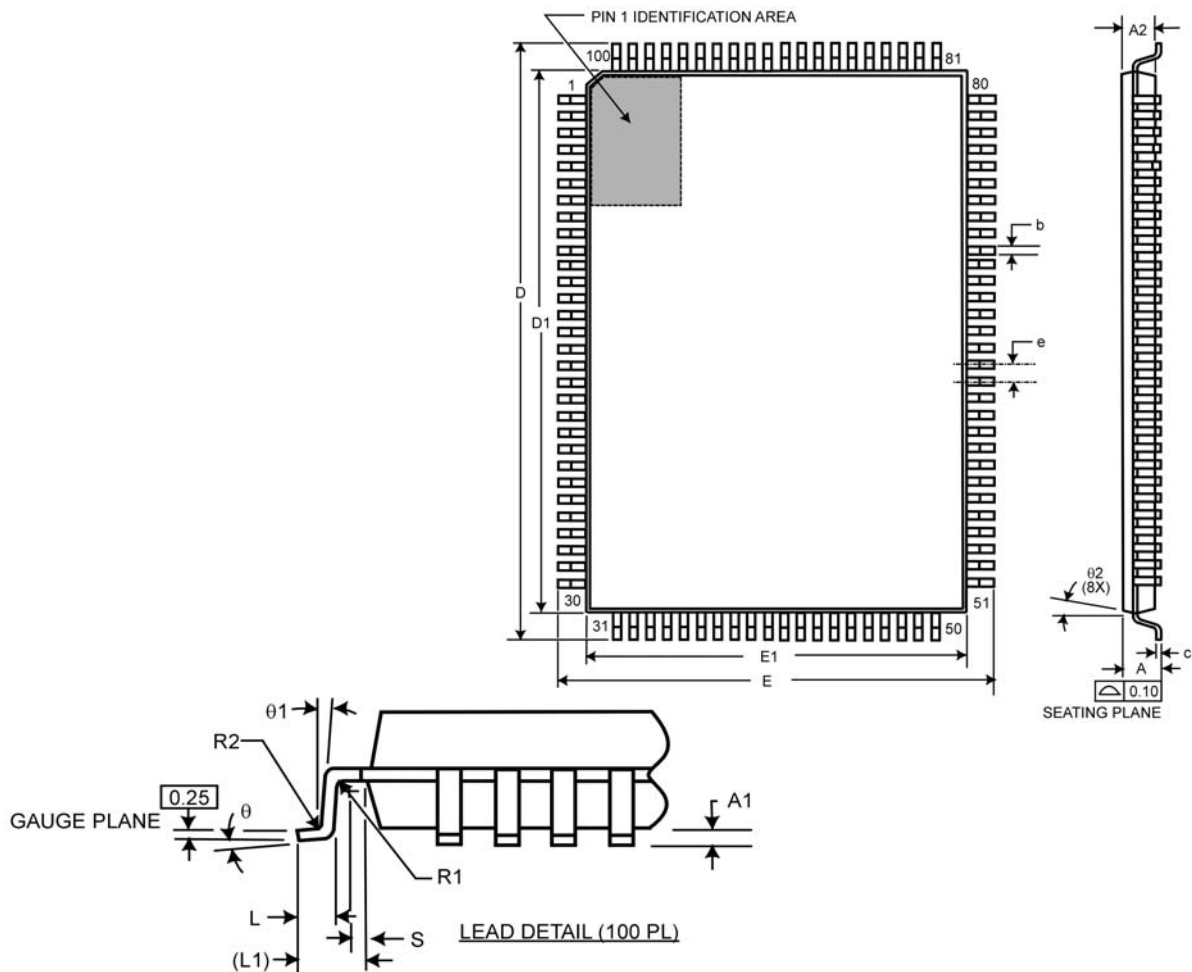
7/ This parameter is sampled and not 100% tested.

8/ Timing reference level is 1.5V when V_{DDQ} = 3.3V and is 1.25V when V_{DDQ} = 2.5V.

9/ Test conditions shown in figure 4 (a), AC Test Loads unless otherwise noted.

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Case X (see notes)



Symbol	Millimeters			Symbol	Millimeters		
	Min	Nom	Max		Min	Nom	Max
A	---	---	1.60	e	---	0.65	---
A1	0.05	---	0.15	L	0.45	0.60	0.75
A2	1.35	1.40	1.45	L1	---	1.00	---
b	0.22	0.30	0.38	R1	0.08	---	0.20
c	---	---	0.20	R2	0.08	---	0.20
D	21.80	22.00	22.20	θ	0°	---	7°
D1	19.90	20.00	20.10	$\theta 1$	0°	---	---
E	15.80	16.00	16.20	$\theta 2$	11°	12°	13°
E1	13.90	14.00	14.10	N	100		

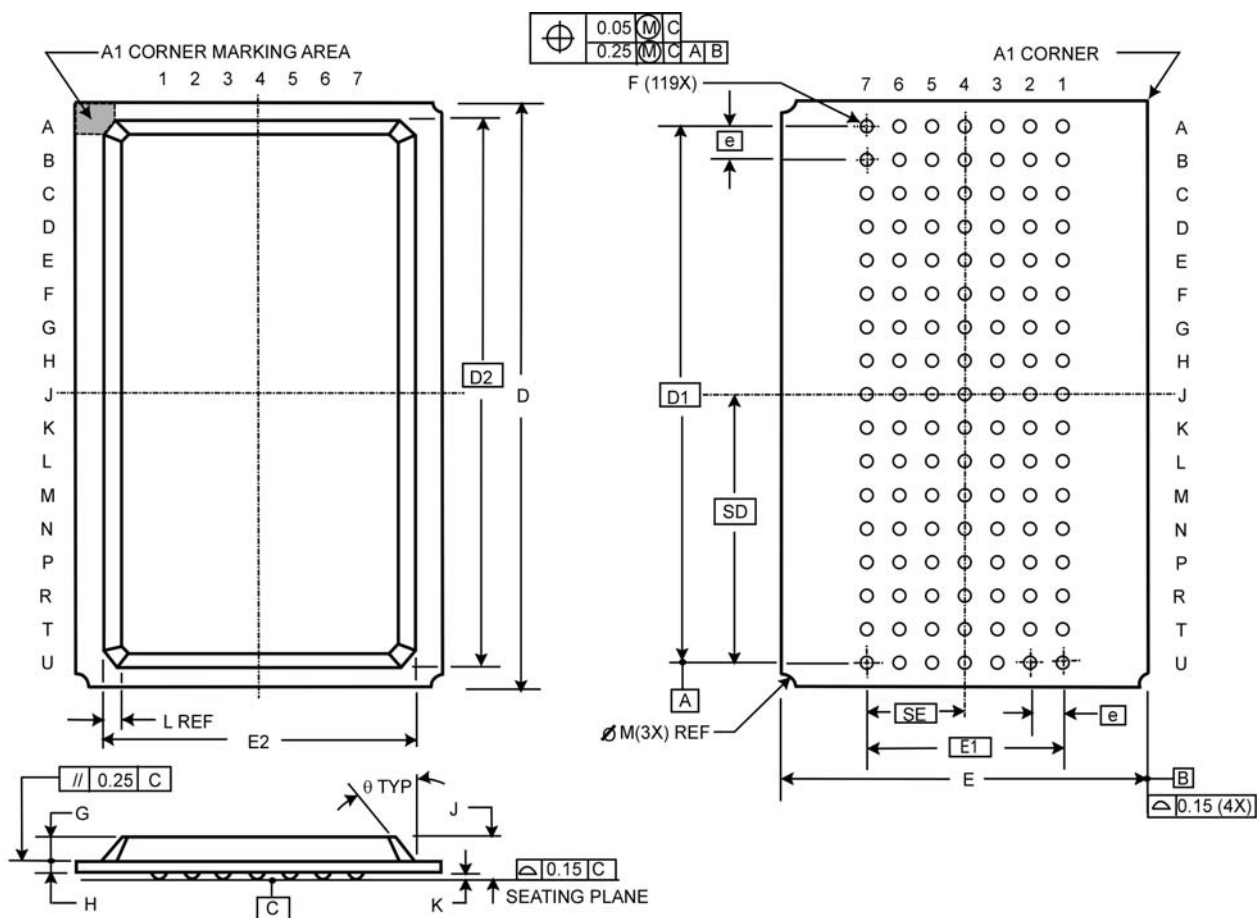
NOTES:

1. Index area: a notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the area shown. The manufacturer's identification shall not be used as pin one identification mark.
2. Ref: JEDEC MS-026 (BHA)

Figure 1. Case outlines.

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Case Y (see notes)



Symbol	Millimeters			Symbol	Millimeters		
	Min	Nom	Max		Min	Nom	Max
D	21.80	22.00	22.20	H	0.51	0.56	0.61
D1	---	20.32	---	J	---	---	2.40
D2	---	19.50	---	K	0.50	0.60	0.70
E	13.80	14.00	14.20	L	---	0.70	---
E1	---	7.62	---	M	---	1.00	---
E2	---	12.00	---	SD	---	10.16	---
e	---	1.27	---	SE	---	3.81	---
F	0.60	0.75	0.90	θ	---	30°	---
G	0.85	0.90	0.95	N	119		

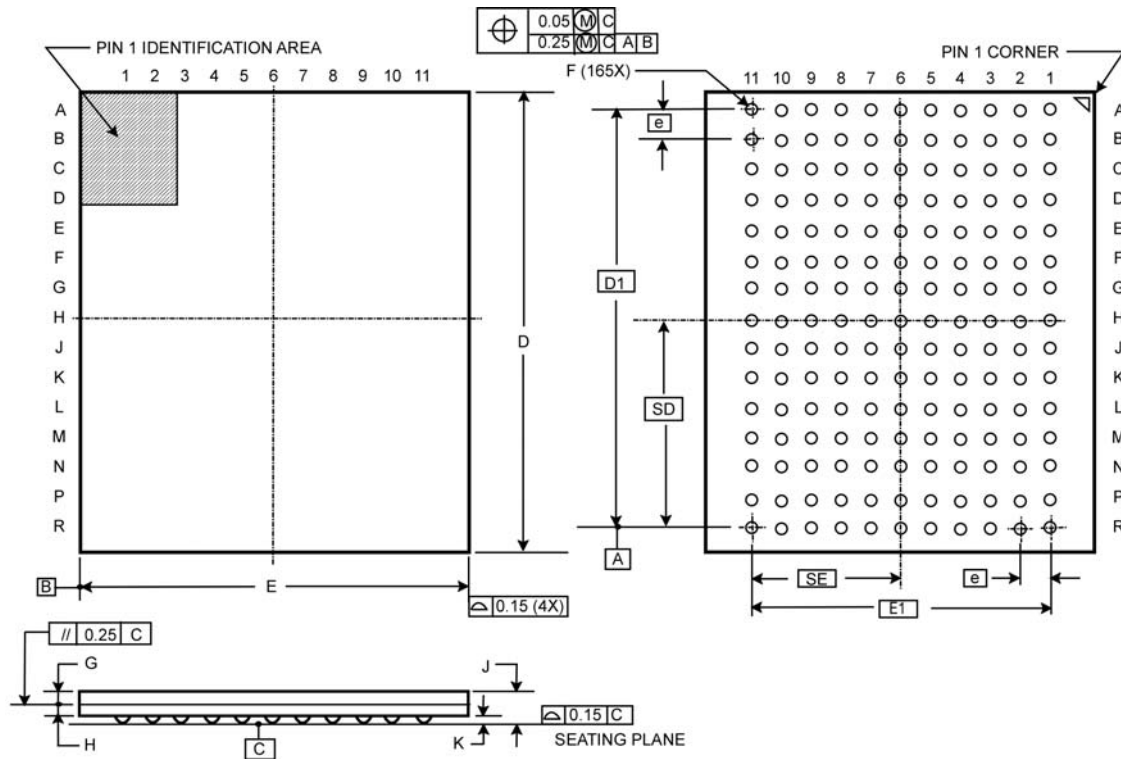
NOTES:

- Index area: a notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the area shown. The manufacturer's identification shall not be used as pin one identification mark.

Figure 1. Case outlines.- continued

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Case Z (see notes)



Symbol	Millimeters			Symbol	Millimeters		
	Min	Nom	Max		Min	Nom	Max
D	14.90	15.00	15.10	H	0.31	0.36	0.41
D1	---	14.00 BSC	---	J	---	---	1.40
E	12.90	13.00	13.10	K	0.29	0.35	0.41
E1	---	10.00 BSC	---	SD	---	7.00 BSC	---
e	---	1.00 BSC	---	SE	---	5.00 BSC	---
f	0.44	0.50	0.64	N	165		
g	0.48	0.53	0.58				
D	14.90	15.00	15.10				

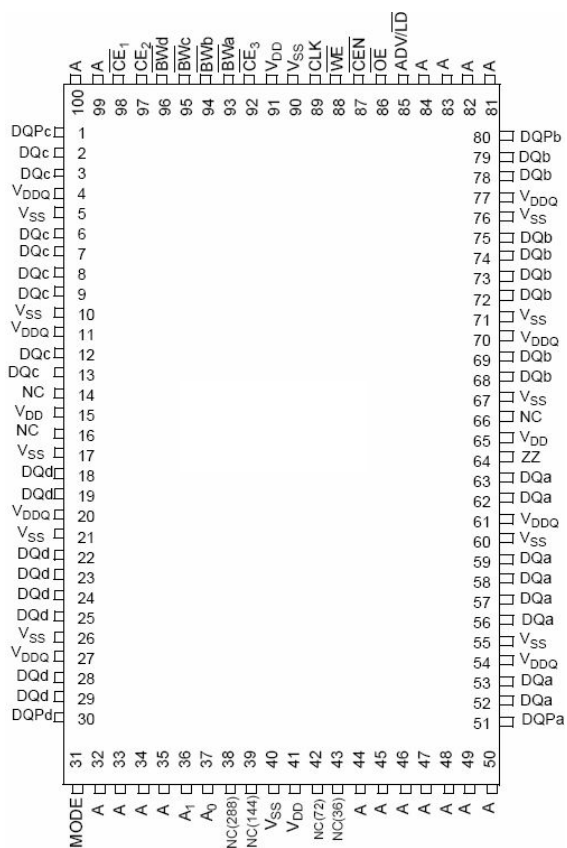
NOTES:

1. Index area: a notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the area shown. The manufacturer's identification shall not be used as pin one identification mark.
2. Ref: JEDEC MO-216 for ball pattern.

Figure 1. Case outlines.- continued

<p align="center">STANDARD MICROCIRCUIT DRAWING</p> <p>DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990</p>	<p align="center">SIZE A</p>		<p align="center">5962-08235</p>
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Case X (100 TQFP)



Case Y (119 BGA)

	1	2	3	4	5	6	7
A	V_{DDQ}	A	A	A	A	A	V_{DDQ}
B	NC/576M	\overline{CE}_2	A	$\overline{ADV/LD}$	A	\overline{CE}_3	NC
C	NC/1G	A	A	V_{DD}	A	A	NC
D	DQ _C	DQP _C	V_{SS}	NC	V_{SS}	DQP _B	DQ _B
E	DQ _C	DQ _C	V_{SS}	\overline{CE}_1	V_{SS}	DQ _B	DQ _B
F	V_{DDQ}	DQ _C	V_{SS}	\overline{OE}	V_{SS}	DQ _B	V_{DDQ}
G	DQ _C	DQ _C	\overline{BW}_C	A	\overline{BW}_B	DQ _B	DQ _B
H	DQ _C	DQ _C	V_{SS}	\overline{WE}	V_{SS}	DQ _B	DQ _B
J	V_{DDQ}	V_{DD}	NC	V_{DD}	NC	V_{DD}	V_{DDQ}
K	DQ _D	DQ _D	V_{SS}	CLK	V_{SS}	DQ _A	DQ _A
L	DQ _D	DQ _D	\overline{BW}_D	NC	\overline{BW}_A	DQ _A	DQ _A
M	V_{DDQ}	DQ _D	V_{SS}	\overline{CEN}	V_{SS}	DQ _A	V_{DDQ}
N	DQ _D	DQ _D	V_{SS}	A ₁	V_{SS}	DQ _A	DQ _A
P	DQ _D	DQP _D	V_{SS}	A ₀	V_{SS}	DQP _A	DQ _A
R	NC/144M	A	MODE	V_{DD}	NC	A	NC/288M
T	NC	NC/72M	A	A	A	NC/36M	ZZ
U	V_{DDQ}	TMS	TDI	TCK	TDO	NC	V_{DDQ}

Figure 2. Terminal connections.

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Case Z (165 FBGA)

	1	2	3	4	5	6	7	8	9	10	11
A	NC/576M	A	\overline{CE}_1	\overline{BW}_C	\overline{BW}_B	\overline{CE}_3	\overline{CEN}	ADV/ \overline{LD}	A	A	NC
B	NC/1G	A	CE_2	\overline{BW}_D	\overline{BW}_A	CLK	\overline{WE}	\overline{OE}	A	A	NC
C	DQP _C	NC	V _{DDQ}	V _{SS}	V _{SS}	V _{SS}	V _{SS}	V _{SS}	V _{DDQ}	NC	DQP _B
D	DQ _C	DQ _C	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	DQ _B	DQ _B
E	DQ _C	DQ _C	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	DQ _B	DQ _B
F	DQ _C	DQ _C	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	DQ _B	DQ _B
G	DQ _C	DQ _C	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	DQ _B	DQ _B
H	NC	NC	NC	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	NC	NC	ZZ
J	DQ _D	DQ _D	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	DQ _A	DQ _A
K	DQ _D	DQ _D	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	DQ _A	DQ _A
L	DQ _D	DQ _D	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	DQ _A	DQ _A
M	DQ _D	DQ _D	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	DQ _A	DQ _A
N	DQP _D	NC	V _{DDQ}	V _{SS}	NC	NC	NC	V _{SS}	V _{DDQ}	NC	DQP _A
P	NC/144M	NC/72M	A	A	TDI	A1	TDO	A	A	A	NC/288M
R	MODE	NC/36M	A	A	TMS	A0	TCK	A	A	A	A

Pin Definitions

Pin	Name	Function
A ₀ , A ₁ , A	Input-Synchronous	Address Inputs used to select one of the address locations. Sampled at the rising edge of the CLK.
\overline{BW}_A , \overline{BW}_B , \overline{BW}_C , \overline{BW}_D	Input-Synchronous	Byte Write Select Inputs, active LOW. Qualified with \overline{WE} to conduct byte writes to the SRAM. Sampled on the rising edge of CLK. \overline{BW}_A controls DQ _A and DQP _A , \overline{BW}_B controls DQ _B and DQP _B , \overline{BW}_C controls DQ _C and DQP _C , \overline{BW}_D controls DQ _D and DQP _D .
\overline{WE}	Input-Synchronous	Write Enable Input, active LOW. Sampled on the rising edge of CLK if \overline{CEN} is active LOW. This signal must be asserted LOW to initiate a write sequence.
ADV/ \overline{LD}	Input-Synchronous	Advance/Load Input used to advance the on-chip address counter or load a new address. When HIGH (and \overline{CEN} is asserted LOW) the internal burst counter is advanced. When LOW, a new address can be loaded into the device for an access. After being deselected, ADV/ \overline{LD} should be driven LOW in order to load a new address.
CLK	Input Clock	Clock Input. Used to capture all synchronous inputs to the device. CLK is qualified with \overline{CEN} . CLK is only recognized if \overline{CEN} is active LOW.
\overline{CE}_1	Input-Synchronous	Chip Enable 1 Input, active LOW. Sampled on the rising edge of CLK. Used in conjunction with CE_2 and \overline{CE}_3 to select/deselect the device.
CE_2	Input-Synchronous	Chip Enable 2 Input, active HIGH. Sampled on the rising edge of CLK. Used in conjunction with \overline{CE}_1 and \overline{CE}_3 to select/deselect the device.
\overline{CE}_3	Input-Synchronous	Chip Enable 3 Input, active LOW. Sampled on the rising edge of CLK. Used in conjunction with \overline{CE}_1 and CE_2 to select/deselect the device.
\overline{OE}	Input-Asynchronous	Output Enable, active LOW. Combine with the synchronous logic block inside the device to control the direction of the I/O pins. When LOW, the I/O pins are allowed to behave as outputs. When deasserted HIGH, I/O pins are tri-stated, and act as input data pins. \overline{OE} is masked during the data portion of a write sequence, during the first clock when emerging from deselected state and when the device has been deselected.
\overline{CEN}	Input-Synchronous	Clock Enable Input, active LOW. When asserted LOW the clock signal is recognized by the SRAM. When deasserted HIGH the clock signal is masked. Since deasserting \overline{CEN} does not deselect the device, \overline{CEN} can be used to extend the previous cycle when required.

Figure 2. Terminal connections. – continued.

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Pin Definitions – continued.

Pin	Name	Function
DQ _S	I/O- Synchronous	Bidirectional Data I/O lines. As inputs, they feed into an on-chip data register that is triggered by the rising edge of CLK. As outputs, they deliver the data contained in the memory location specified by $A_{[17:0]}$ during the previous clock rise of the read cycle. The direction of the pins is controlled by \overline{OE} and the internal control logic. When \overline{OE} is asserted LOW, the pins can behave as outputs. When HIGH, $DQ_A - DQ_D$ are placed in a tri-state condition. The outputs are automatically tri-stated during the data portion of a write sequence, during the first clock when emerging from a deselected state, and when the device is deselected, regardless of the state of \overline{OE} .
DQP _X	I/O- Synchronous	Bidirectional DataParity I/O lines. Functionally, these signals are identical to DQ _S . During write sequences, DQP _A is controlled by \overline{BW}_A , DQP _B is controlled by \overline{BW}_B , DQP _C is controlled by \overline{BW}_C and DQP _D is controlled by \overline{BW}_D .
MODE	Input Strap Pin	Mode Input. Selects the burst order of the device. Tied HIGH selects the interleaved burst order. Pulled LOW selects the linear burst order. MODE should not change states during operation. When left floating MODE will default HIGH, to an interleaved burst order.
TDO	JTAG serial output Synchronous	Serial data-out to the JTAG circuit. Delivers data on the negative edge of TCK
TDI	JTAG serial input Synchronous	Serial data-in to the JTAG circuit. Sampled on the rising edge of TCK.
TMS	Test Mode Select Synchronous	This pin controls the Test Access Port state machine. Sampled on the rising edge of TCK.
TCK	JTAG - Clock	Clock input to the JTAG circuitry.
V _{DD}	Power Supply	Power Supply Inputs to the core of the device.
V _{SS}	Ground	Ground for the core of the device.
V _{DDQ}	I/O Power Supply	Power Supply for the I/O circuitry.
ZZ	Input-Asynchronous	ZZ “sleep” Input. This active HIGH input places the device in a non-time critical “sleep” condition with data integrity preserved. During normal operation, this pin can be connected to V _{SS} or left floating. ZZ pins has an internal pull-down.
NC	---	No Connects. This pin is not connected to the die.
NC/(36M, 72M, 144M, 288M, 576M, 1G)	---	These pins are not connected. They will be used for expansion to the 36M, 72M, 144M, 288M, 576M and 1G densities.

FIGURE 2. Terminal connections. - continued

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Truth Table 1/ 2/ 3/ 4/ 5/ 6/ 7/

Operation	Address Used	CE	ZZ	ADV/LD	WE	BW _x	OE	CEN	CLK	DQ
Deselect Cycle	None	H	L	L	X	X	X	L	L-H	Tri-State
Continue Deselect Cycle	None	X	L	H	X	X	X	L	L-H	Tri-State
Read Cycle (Begin Burst)	External	L	L	L	H	X	L	L	L-H	Data Out (Q)
Read Cycle (Continue Burst)	Next	X	L	H	X	X	L	L	L-H	Data Out (Q)
NOP/Dummy Read (Begin Burst)	External	L	L	L	H	X	H	L	L-H	Tri-State
Dummy Read (Continue Burst)	Next	X	L	H	X	X	H	L	L-H	Tri-State
Write Cycle (Begin Burst)	External	L	L	L	L	L	X	L	L-H	Data In (D)
Write Cycle (Continue Burst)	Next	X	L	H	X	L	X	L	L-H	Data In (D)
NOP/Write Abort (Begin Burst)	None	L	L	L	L	H	X	L	L-H	Tri-State
Write Abort (Continue Burst)	Next	X	L	H	X	H	X	L	L-H	Tri-State
Ignore Clock Edge (Stall)	Current	X	L	X	X	X	X	H	L-H	---
Sleep Mode	None	X	H	X	X	X	X	X	X	Tri-State

Partial Truth Table for Read/Write 1/ 2/ 3/ 8/

Function	WE	BW _D	BW _C	BW _B	BW _A
Read	H	X	X	X	X
Write – No bytes written	L	H	H	H	H
Write Byte A - (DQ _A and DQP _A)	L	H	H	H	L
Write Byte B - (DQ _B and DQP _B)	L	H	H	L	H
Write Bytes B, A	L	H	H	L	L
Write Byte C- (DQ _C and DQP _C)	L	H	L	H	H
Write Bytes C, A	L	H	L	H	L
Write Bytes C, B	L	H	L	L	H
Write Bytes C, B, A	L	H	L	L	L
Write Byte D – (DQ _D and DQP _D)	L	L	H	H	H
Write Bytes D, A	L	L	H	H	L
Write Bytes D, B	L	L	H	L	H
Write Bytes D, B, A	L	L	H	L	L
Write Bytes D, C	L	L	L	H	H
Write Bytes D, C, A	L	L	L	H	L
Write Bytes D, C, B	L	L	L	L	H
Write All Bytes	L	L	L	L	L

Notes:

- 1/ X = "Don't Care." H = Logic HIGH, L = Logic LOW, CE stands for ALL Chip Enables active. BW_x = L signifies at least one Byte Write Select is active, BW_x = Valid signifies that the desired byte write selects are asserted, see Truth Table for details.
- 2/ Write is defined by WE and BW_x. See Truth Table for details.
- 3/ When a write cycle is detected, all I/Os are tri-stated, even during byte writes.
- 4/ The DQ and DQP pins are controlled by the current cycle and the OE signal.
- 5/ CEN = H inserts wait states.
- 6/ Device will power-up deselected and the I/Os in a tri-state condition regardless of OE.
- 7/ OE is asynchronous and is not sampled with the clock rise. It is masked internally during write cycles. During a read cycle DQs and DQP_x = Three-state when OE is inactive or when the device is deselected, and DQs = data when OE is active.
- 8/ Table only lists a partial listing of the byte write combinations. Any combination of BW_x is valid. Appropriate write will be done based on which byte write is active.

Figure 3. Truth table and device operations.

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Interleaved Burst Address Table
(MODE = Floating or V_{DD})

First Address A ₁ , A ₀	Second Address A ₁ , A ₀	Third Address A ₁ , A ₀	Fourth Address A ₁ , A ₀
00	01	10	11
01	00	11	10
10	11	00	01
11	10	01	00

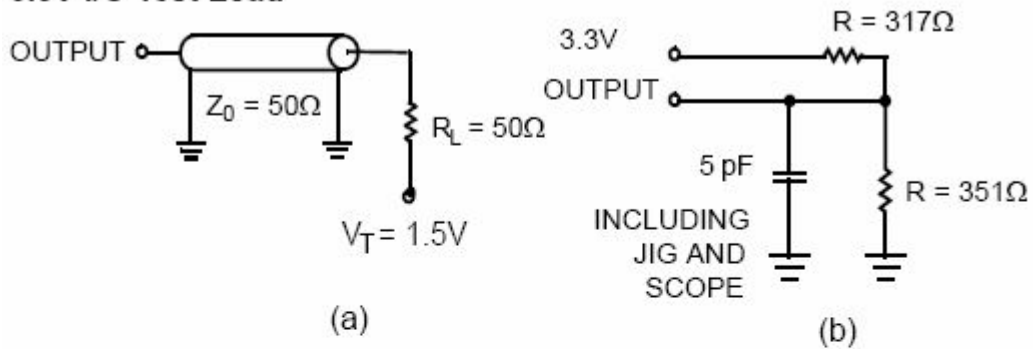
Linear Burst Address Table
(MODE = GND)

First Address A ₁ , A ₀	Second Address A ₁ , A ₀	Third Address A ₁ , A ₀	Fourth Address A ₁ , A ₀
00	01	10	11
01	10	11	00
10	11	00	01
11	00	01	10

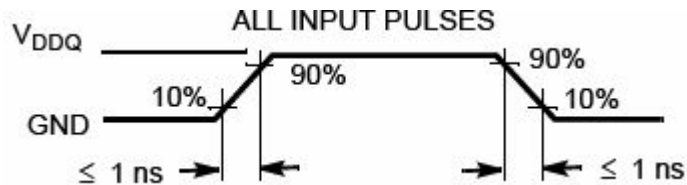
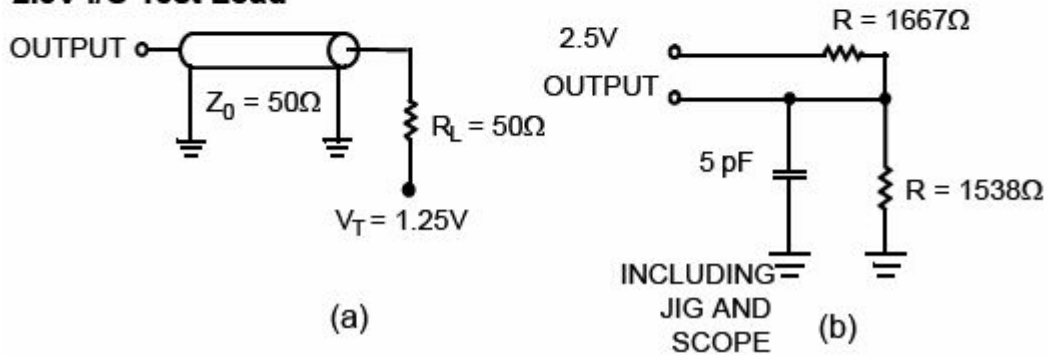
Figure 3. Truth table and device operations.—continued.

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3.3V I/O Test Load



2.5V I/O Test Load



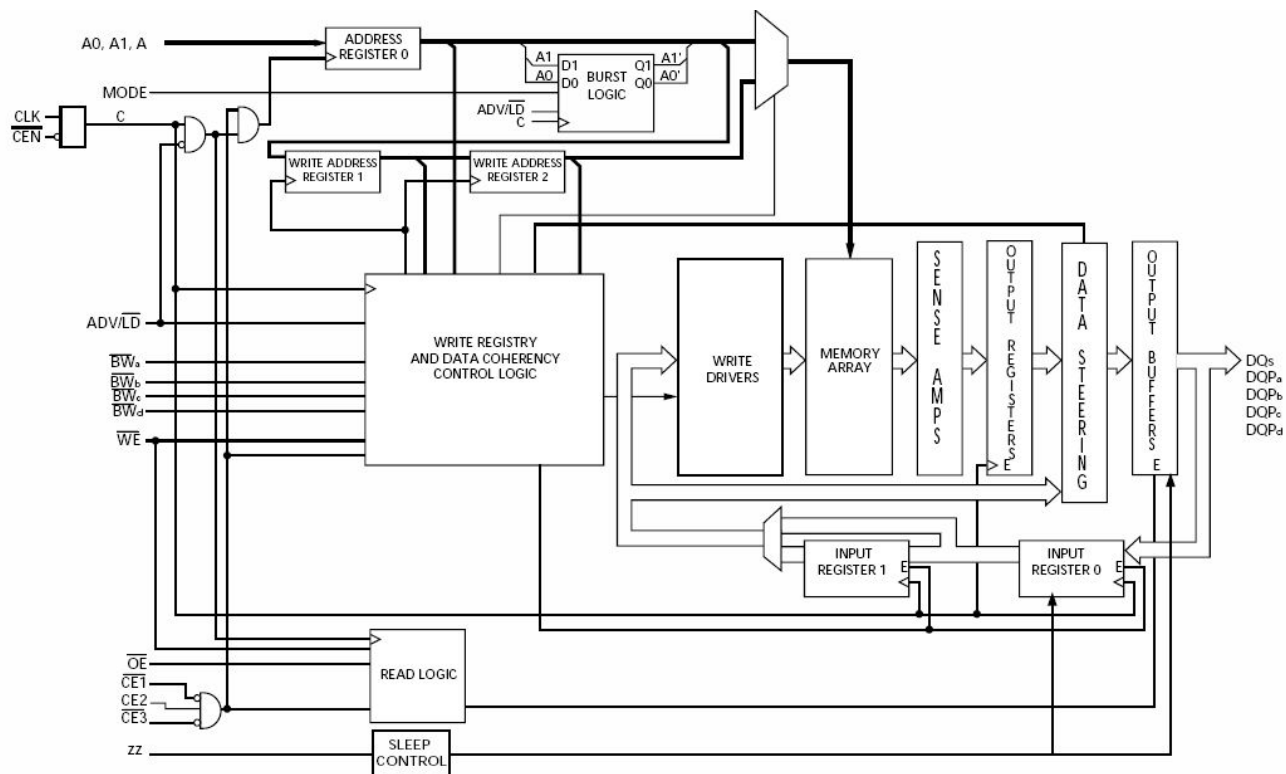
NOTES:

1. Use these output load circuits or equivalent for testing.
2. Capacitive load consists of all components of the test environment, including jig and scope.

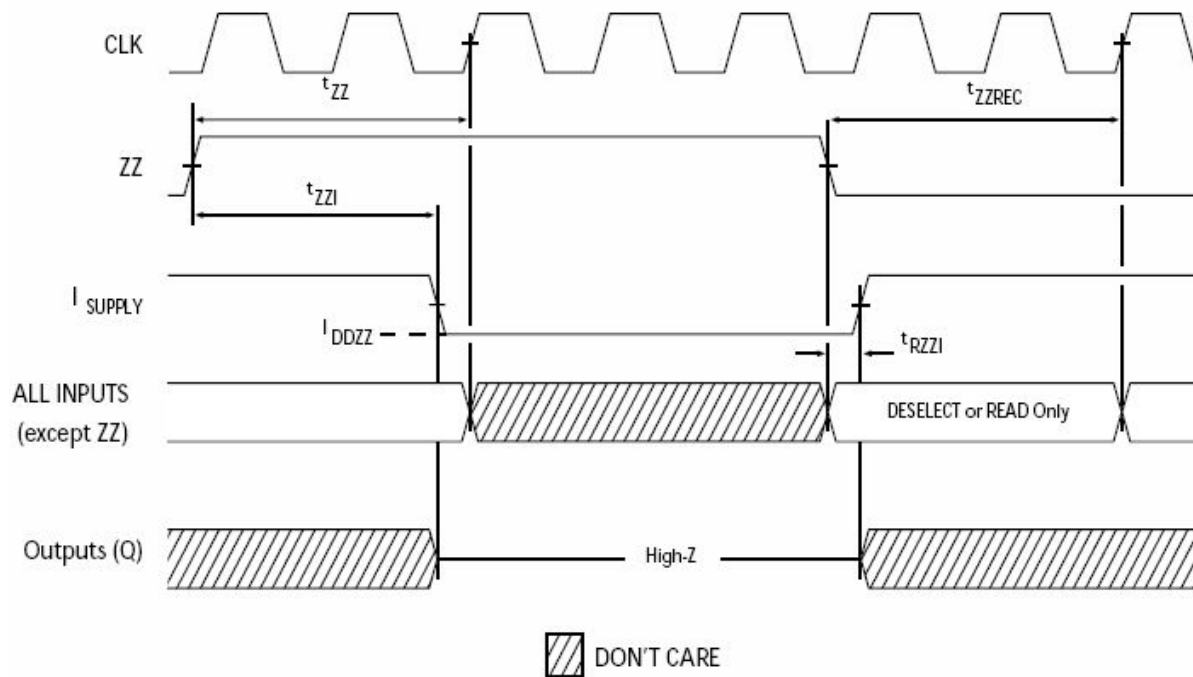
Figure 4. Output load circuits.

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BLOCK DIAGRAM



ZZ MODE TIMING 1/ 2/



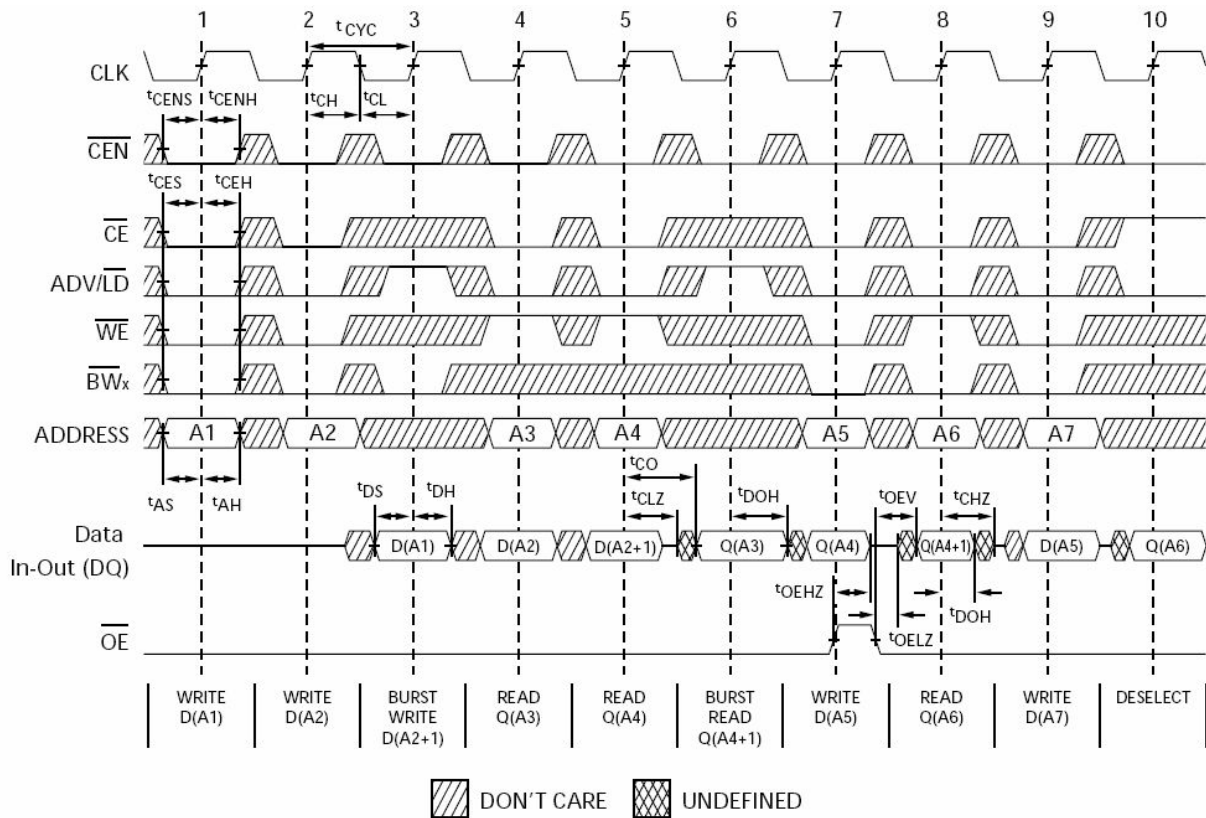
NOTES:

- 1/ Device must be deselected when entering ZZ mode. See the Truth Table for all possible signal conditions to deselect the device.
- 2/ I/Os are in high-Z when exiting ZZ sleep mode.

Figure 5. Timing waveforms.

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READ/WRITE CYCLE TIMING 3/ 4/ 5/



NOTES:

3/ For this waveform ZZ is tied LOW.

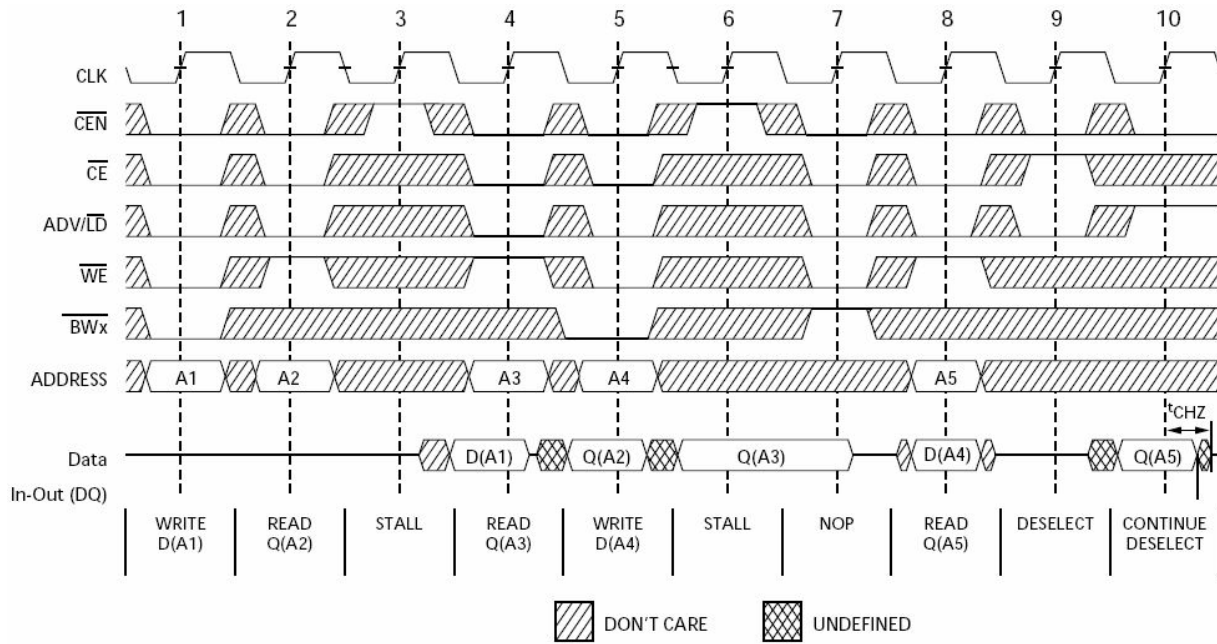
4/ On this diagram, when \overline{CE} is LOW, \overline{CE}_1 is LOW, CE_2 is HIGH and \overline{CE}_3 is LOW. When \overline{CE} is HIGH, \overline{CE}_1 is HIGH or CE_2 is LOW or \overline{CE}_3 is HIGH.

5/ Order of the Burst sequence is determined by the status of the MODE (0 = Linear, 1 = Interleaved). Burst operations are optional.

Figure 5. Timing waveforms - continued

<p align="center">STANDARD MICROCIRCUIT DRAWING</p> <p>DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990</p>	<p align="center">SIZE A</p>		<p align="center">5962-08235</p>
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NOP, STALL AND DESELECT CYCLE TIMING 3/ 4/ 6/



NOTES:

6/ The Ignore Clock Edge or Stall cycle (Clock 3) illustrated $\overline{\text{CEN}}$ being used to create a pause. A write is not preformed during this cycle.

Figure 5. Timing waveforms - continued

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TABLE IIA. Electrical test requirements. 1/ 2/ 3/ 4/ 5/ 6/ 7/ 8/

Line No.	Test Requirements	Subgroups (In accordance with MIL-PRF-38535, Table III)		
		Device Class N	Device Class Q	Device Class V
1	Interim electrical parameters (See 4.2)			1, 7, 9
2	Static Burn-In I Method 1015	Not Required	Not required	Required
3	Same as Line 1			1*, 7* Δ
4	Dynamic Burn-In (Method 1015)	Required	Required	Required
5	Same as Line 1			1*, 7* Δ
6	Final Electrical Parameters	1*, 2, 3, 7*, 8A, 8B, 9, 10, 11	1*, 2, 3, 7*, 8A, 8B, 9, 10, 11	1*, 2, 3, 7*, 8A, 8B, 9, 10, 11
7	Group A Test Requirements	1, 2, 3, 4**, 7, 8A, 8B, 9, 10, 11	1, 2, 3, 4**, 7, 8A, 8B, 9, 10, 11	1, 2, 3, 4**, 7, 8A, 8B, 9, 10, 11
8	Group C End-Point Electrical Parameters	2, 3, 7, 8A, 8B	2, 3, 7, 8A, 8B	1, 2, 3, 7, 8A, 8B, 9, 10, 11 Δ
9	Group D End-Point Electrical Parameters	2, 3, 8A, 8B	2, 3, 8A, 8B	2, 3, 8A, 8B
10	Group E End-Point Electrical Parameters	1, 7, 9	1, 7, 9	1, 7, 9

1/ Blank spaces indicate tests are not applicable.

2/ Any or all subgroups may be combined when using high-speed testers.

3/ Subgroups 7 and 8 functional tests shall verify the truth table.

4/ * indicates PDA applies to subgroup 1 and 7.

5/ ** see 4.4.1e.

6/ Δ indicates delta limit (see table IIB) shall be required where specified, and the delta values shall be computed with reference to the previous interim electrical parameters (see line 1).

7/ See 4.4.1d.

8/ Group A testing is not required if the requirements of MIL-PRF-38535 appendix B paragraph (B.4.2.a) have been accomplished.

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TABLE IIB. Delta limits at +25°C.

Parameter <u>1/</u>	All device types
I _{SB2} , I _{SB4} standby	±10% of specified value in table I
I _x , I _{OZ}	±10% of specified value in table I

1/ The above parameter shall be recorded before and after the required burn-in and life tests to determine the delta.

4. VERIFICATION

4.1 Sampling and inspection. For device classes N, Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

4.2 Screening. For device classes N, Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection.

4.2.1 Additional criteria for device classes N, Q and V.

- a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
- b. Interim and final electrical test parameters shall be as specified in table IIA herein.
- c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 Qualification inspection for device classes N, Q and V. Qualification inspection for device classes N, Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 Conformance inspection. Technology conformance inspection for classes N, Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified herein.

4.4.1 Group A inspection.

- a. Tests shall be as specified in table IIA herein. Group A testing is not required if all tests have been performed during final electrical of the 100% Screening test. See footnote g/ for table IIA.
- b. Subgroups 5 and 6 of table I of method 5005 of MIL-STD-883 shall be omitted.
- c. O/V (latch-up) tests shall be measured only for initial qualification and after any design or process changes which may affect the performance of the device. For device classes N, Q and V, the procedures and circuits shall be under the control of the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the preparing activity or acquiring activity upon request. Testing shall be on all pins, on five devices with zero failures. Latch-up test shall be considered destructive. Information contained in JEDEC Standard EIA/JESD78 may be used for reference.
- d. Subgroup 4 (C_{IN} and C_{OUT} measurements) shall be measured only for initial qualification and after any process or design changes which may affect input or output capacitance. Capacitance shall be measured between the designated terminal and GND at a frequency of 1 MHz. Sample size is 5 devices with no failures, and all input and output terminals tested.

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4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.2.1 Additional criteria for device classes N, Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.4 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

- a. End-point electrical parameters shall be as specified in table IIA herein.
- b. For device classes N, Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at $T_A = +25^{\circ}\text{C} \pm 5^{\circ}\text{C}$, after exposure, to the subgroups specified in table IIA herein.
- c. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.

4.5 Delta measurements for device class V. Delta measurements, as specified in table IIA, shall be made and recorded before and after the required burn-in screens and steady-state life tests to determine delta compliance. The electrical parameters to be measured, with associated delta limits are listed in table IIB. The device manufacturer may, at his option, either perform delta measurements or within 24 hours after burn-in perform final electrical parameter tests, subgroups 1, 7, and 9.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes N, Q and V.

5.2 Special Class N handling. Class N device is rated as a Moisture Sensitivity Level 3 part when tested per J-STD-020A. Device will be baked and dry packed when shipped from the manufacturer. Device will require a 125°C dry bake for 24 hours prior to installation if prolonged exposure on normal factory floor of the end user has occurred.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor prepared specification or drawing.

6.2 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.3 Record of users. Military and industrial users should inform Defense Supply Center Columbus (DSCC) when a system application requires configuration control and which SMD's are applicable to that system. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.

6.4 Comments. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43216-5000, or telephone (614) 692-0547.




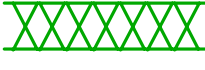
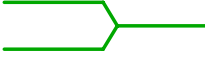
6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.5.1 Timing limits. The table of timing values shows either a minimum or a maximum limit for each parameter. Input requirements are specified from the external system point of view. Thus, address setup time is shown as a minimum since the

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system must supply at least that much time (even though most devices do not require it). On the other hand, responses from the memory are specified from the device point of view. Thus, the access time is shown as a maximum since the device never provides data later than that time.

6.5.2 Waveforms.

Waveform symbol	Input	Output
	MUST BE VALID	WILL BE VALID
	CHANGE FROM H TO L	WILL CHANGE FROM H TO L
	CHANGE FROM L TO H	WILL CHANGE FROM L TO H
	DON'T CARE ANY CHANGE PERMITTED	CHANGING STATE UNKNOWN
		HIGH IMPEDANCE

6.6 Sources of supply.

6.6.1 Sources of supply for device classes N, Q and V. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DSCC-VA and have agreed to this drawing.

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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 09-XX-XX

Approved sources of supply for SMD 5962-08SMD are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>
5962-0823501NXA	6S055	DPA1370D25003A
5962-0823502NXA	6S055	DPA1370D20003A
5962-0823503NXA	6S055	DPA1370D16703A
5962-0823501NYA	6S055	DPA1370D25004A
5962-0823502NYA	6S055	DPA1370D20004A
5962-0823503NYA	6S055	DPA1370D16704A
5962-0823501NZA	6S055	DPA1370D25005A
5962-0823502NZA	6S055	DPA1370D20005A
5962-0823503NZA	6S055	DPA1370D16705A

1/ The lead finish shown for each PIN is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.

2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE
number

6S055

Vendor name
and address

DPA Components International
2251 Ward Avenue
Simi Valley, CA 93065

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.